

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
22 September 2005 (22.09.2005)

PCT

(10) International Publication Number
WO 2005/088715 A1

(51) International Patent Classification⁷: **H01L 23/525**

(21) International Application Number:

PCT/US2005/005671

(22) International Filing Date: 23 February 2005 (23.02.2005)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:

10/789,637 27 February 2004 (27.02.2004) US

(63) Related by continuation (CON) or continuation-in-part (CIP) to earlier application:

US 10/789,637 (CON)
Filed on 27 February 2004 (27.02.2004)

(71) Applicant (for all designated States except US): **NVIDIA CORPORATION** [US/US]; 2701 San Tomas Expressway, Santa Clara, California 95050 (US).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **SCHIECK, Brian, S.** [US/US]; 535 Eleanor Place, Hayward, California 94544

(US). **MARKS, Howard, Lee** [US/US]; 7551 Troon Court, Gilroy, California 95020 (US).

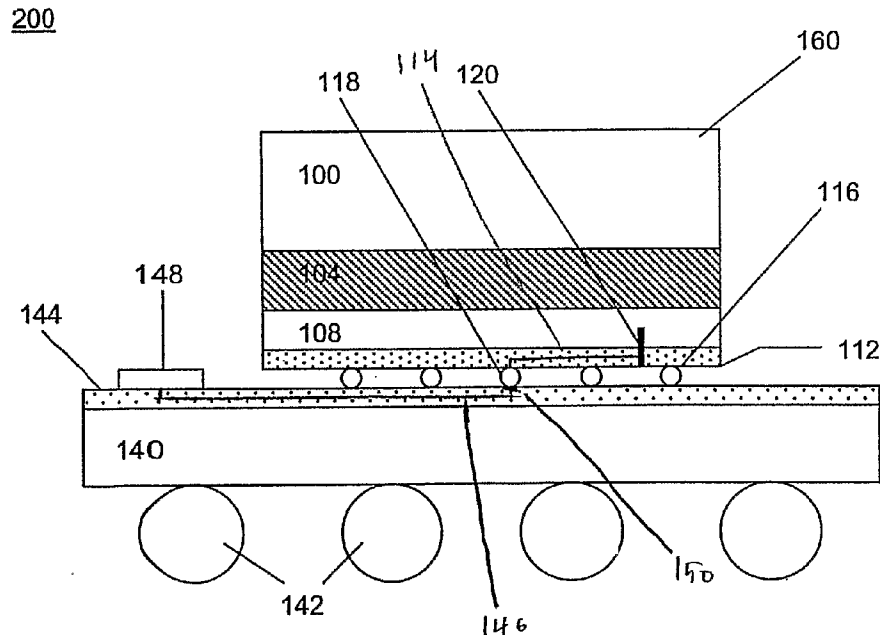
(74) Agents: **GALLENSON, Mavis, S.** et al.; LADAS & PARRY LLP, 5670 Wilshire Boulevard, Suite 2100, Los Angeles, California 90036-5679 (US).

(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SM, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, MC, NL, PL, PT, RO,

[Continued on next page]

(54) Title: SYSTEM AND METHOD PERTAINING TO SEMICONDUCTOR DIES



(57) Abstract: A device and method for providing access to a signal of a flip chip semiconductor die (160). A hole is bored into a semiconductor die to a test probe point. The hole is backfilled with a conductive material (120), electrically coupling the test probe point to a signal redistribution layer. A conductive bump (118) of the signal redistribution layer (112) is electrically coupled to a conductive contact (150) of a package substrate (140). An external access point (148) of the package substrate is electrically coupled to the conductive contact, such that signals of the flip chip semiconductor die are accessible for measurement at the external access point (148).

WO 2005/088715 A1



SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

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Published:

— *with international search report*